


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MICROCONTROLLERS/24/14976	
1.3 Title of PCN	JSCC (China) LQFP7x7 48L , LQFP10x10 64L package copper palladium bonding wire introduction on STM32F2x, STM32F4x and STM32F7x listed products	
1.4 Product Category	STM32F20x / STM32F21x, STM32F40x / STM32F41x , STM32F42x / STM32F44x, STM32F72x / STM32F73x,	
1.5 Issue date	2024-12-04	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Direct Material: Bond Wire - Metallurgy (metallic composition/ raw material)	StatsChipPAC JSCC Jiangyin (China)

4. Description of change

	Old	New
4.1 Description	Current Wire bonding material: - JSCC (China) Gold wire or Silver wire - AMKOR ATP (Philippines) gold wire - ASE Kaohsiung (Taiwan) Gold wire or Copper Palladium wire	Current Wire bonding material: - JSCC (China) Gold wire or Silver wire - AMKOR ATP (Philippines) gold wire - ASE Kaohsiung (Taiwan) Gold wire or Copper Palladium wire Added Wire bonding material : - JSCC (China) Copper Palladium wire
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact on form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	To improve service
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST Internal tools
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7. Timing / schedule

7.1 Date of qualification results	2025-02-03
7.2 Intended start of delivery	2025-02-03
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	14976 MDRF-GPM-RER2321 V5.0 - PCN14363 - PCN14922 - PCN14976 JSCC (China) LQ7 LQ10 and LQ12 CuPd - reliab report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2024-12-04

9. Attachments (additional documentations)

14976 Public product.pdf
 14976 MDRF-GPM-RER2321 V5.0 - PCN14363 - PCN14922 - PCN14976 JSCC (China) LQ7 LQ10 and LQ12 CuPd - reliab report.pdf
 14976 _Additional information.pdf

10. Affected parts

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F205RBT6	
	STM32F205RBT6TR	
	STM32F205RBT7	
	STM32F205RCT6	
	STM32F205RCT6TR	
	STM32F205RCT7	
	STM32F205RCT7TR	
	STM32F205RET6	
	STM32F205RET6TR	
	STM32F205RET7	
	STM32F205RFT6	
	STM32F205RFT6TR	
	STM32F205RGT6	
	STM32F205RGT6TR	
	STM32F205RGT7	
	STM32F215RET6	
	STM32F215RGT6	
	STM32F215RGT6TR	
	STM32F401RBT6	
	STM32F401RBT6TR	
	STM32F401RCT6	
	STM32F401RCT6TR	
	STM32F401RCT7TR	
	STM32F401RDT6	
	STM32F401RDT6TR	
	STM32F401RET6	
	STM32F401RET6TR	
	STM32F401RET6U	
	STM32F401RET7	
	STM32F405RGT6	
	STM32F405RGT6TR	
	STM32F405RGT7	
	STM32F405RGT7TR	
	STM32F410CBT3	
	STM32F410CBT6	
	STM32F410R8T6	
	STM32F410RBT6	
	STM32F410RBT6TR	
	STM32F410RBT7	
	STM32F410RBT7TR	
	STM32F411RCT6	
	STM32F411RCT6TR	
	STM32F411RET6	
	STM32F411RET6TR	

	STM32F411RET7	
	STM32F412RET6	
	STM32F412RET6TR	
	STM32F412RET7	
	STM32F412RGT6	
	STM32F412RGT6TR	
	STM32F413RGT6	
	STM32F413RGT6TR	
	STM32F413RHT3	
	STM32F413RHT6	
	STM32F415RGT6	
	STM32F415RGT6TR	
	STM32F423RHT6	
	STM32F423RHT6TR	
	STM32F446RCT6	
	STM32F446RCT6TR	
	STM32F446RCT7	
	STM32F446RET6	
	STM32F446RET6TR	
	STM32F446RET7	
	STM32F446RET7TR	
	STM32F722RCT6	
	STM32F722RET6	
	STM32F722RET7	
	STM32F730R8T6	
	STM32F732RET6	
	STM32F405RGT6U	
	STM32F411RCT6GEM	
	STM32F446RCT7TR	
	STM32F205RGT6V	
	STM32F205RGT6W	
	STM32F405RGT6V	
	STM32F405RGT6W	

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